

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE0224F uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

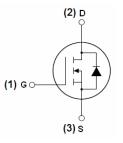
- V_{DS} =200V, I_{D} =24A $R_{DS(ON)}$ < 80mΩ @ V_{GS} =10V (Typ:64mΩ)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% AVds TESTED!



Schematic diagram



Marking and pin assignment



TO-220F top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE0224F	NCE0224F	TO-220F	-	-	-

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	200	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	24	А
Drain Current-Continuous(T _C =100°C)	I _D (100℃)	16.5	Α
Pulsed Drain Current	I _{DM}	72	Α
Maximum Power Dissipation	P _D	45	W
Single pulse avalanche energy (Note 5)	E _{AS}	250	mJ
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 175	$^{\circ}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	3.33	°C/W
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Electrical Characteristics (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	200	220	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =200V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20V, V_{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	•		•			
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	2.5	3.2	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	64	80	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =20A	30	-	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}	\/ -400\/\/ -0\/		4565.8		PF
Output Capacitance	Coss	V _{DS} =100V,V _{GS} =0V,		87.2		PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz			PF	
Switching Characteristics (Note 4)	•		•			
Turn-on Delay Time	t _{d(on)}		-	15	-	nS
Turn-on Rise Time	t _r	V_{DD} =100 V , I_{D} =20 A	-	20	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{GEN} =2.5 Ω	-	30	-	nS
Turn-Off Fall Time	t _f		-	9	-	nS
Total Gate Charge	Qg	V -400V/I -20A		91.9		nC
Gate-Source Charge	Q _{gs}	V_{DS} =100V, I_{D} =20A, V_{GS} =10V		21.8		nC
Gate-Drain Charge	Q_{gd}	V _{GS} -10V		29.9		nC
Drain-Source Diode Characteristics	•		•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-	-	1.2	V
Diode Forward Current (Note 2)	Is	-	-	-	24	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 20A	-	51	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	75	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				y LS+LD)

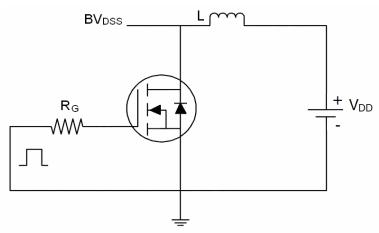
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition:Tj=25 $^{\circ}\text{C}$,VDD=100V,VG=10V,L=0.5mH,Rg=25 Ω

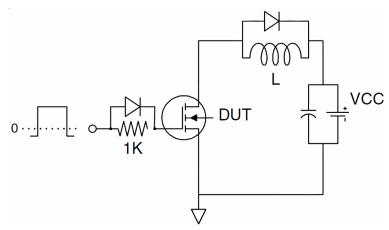


Test Circuit

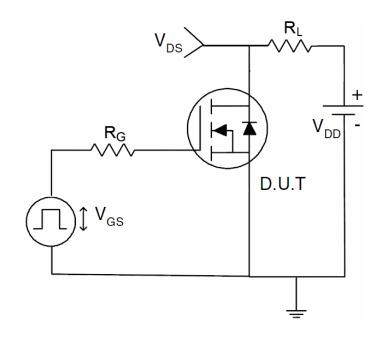
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit



3) Switch Time Test Circuit





Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	200	220	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =200V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	2.5	3.2	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	64	80	mΩ
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Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}	\/ -400\/\/ -0\/		4565.8		PF
Output Capacitance	Coss	V_{DS} =100V, V_{GS} =0V, F=1.0MHz		87.2		PF
Reverse Transfer Capacitance	C _{rss}	r=1.0lvln2		70		PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	15	-	nS
Turn-on Rise Time	t _r	V_{DD} =100 V , I_{D} =20 A	-	20	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{GEN} =2.5 Ω	_	30	-	nS
Turn-Off Fall Time	t _f		-	9	-	nS
Total Gate Charge	Qg	V -400V/I -20A		91.9		nC
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Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 20A	-	51	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	75	-	nC
Forward Turn-On Time	ton	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				y LS+LD)

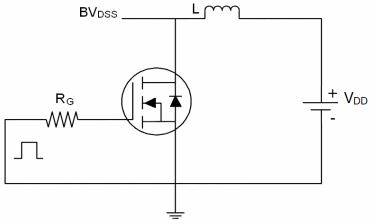
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25 $^{\circ}\text{C}$,VDD=100V,VG=10V,L=0.5mH,Rg=25 Ω
- 6. The spike duty cycle 5% max, limited by junction temperature $T_{J}(MAX)\text{=}125\,^{\circ}\,$ C

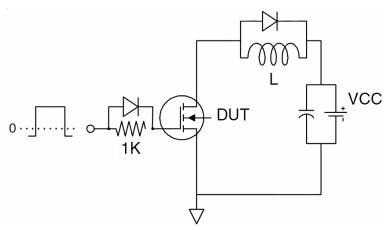


Test Circuit

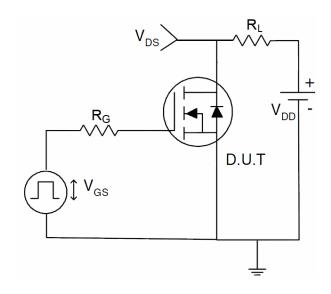
1) E_{AS} test Circuits



2) Gate charge test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

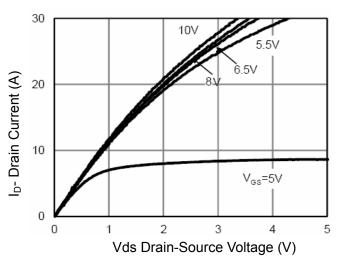


Figure 1 Output Characteristics

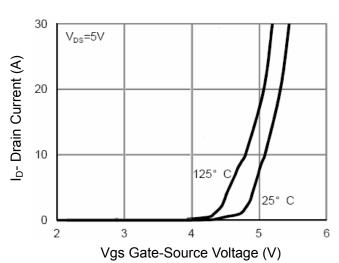


Figure 2 Transfer Characteristics

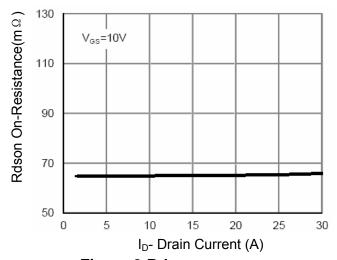


Figure 3 Rdson- Drain Current

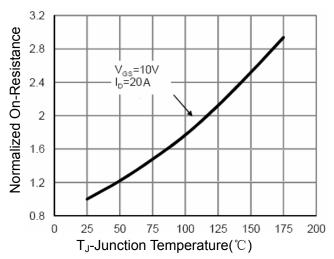


Figure 4 Rdson-JunctionTemperature

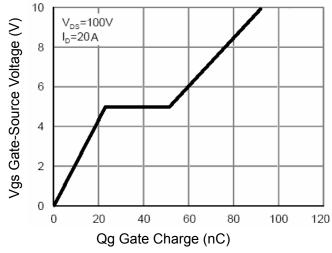


Figure 5 Gate Charge

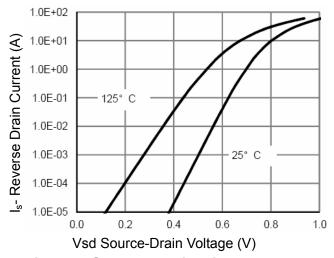


Figure 6 Source- Drain Diode Forward



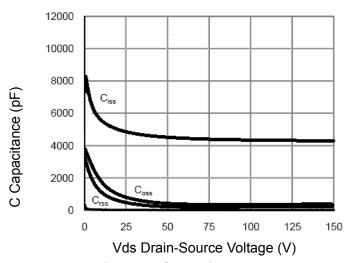
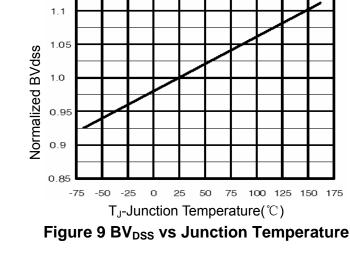


Figure 7 Capacitance vs Vds



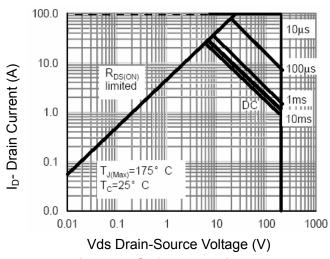


Figure 8 Safe Operation Area

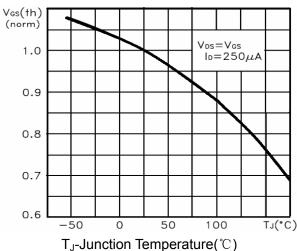


Figure 10 V_{GS(th)} vs Junction Temperature

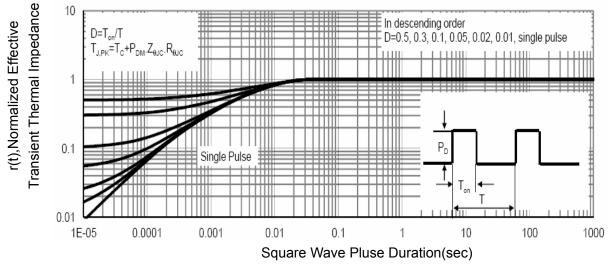
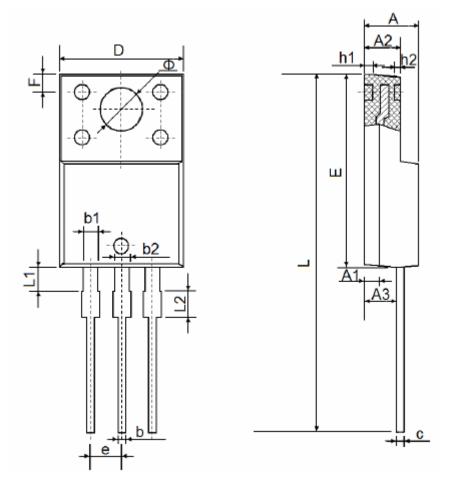


Figure 11 Normalized Maximum Transient Thermal Impedance



TO-220F Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	4.300	4.700	0.169	0.185	
A1	1.30	00REF	0.051REF		
A2	2.800	3.200	0.110	0.126	
A3	2.500	2.900	0.098	0.114	
b	0.500	0.750	0.020	0.030	
b1	1.100	1.350	0.043	0.053	
b2	1.500	1.750	0.059	0.069	
С	0.500	0.750	0.020	0.030	
D	9.960	10.360	0.392	0.408	
E	14.800	15.200	0.583	0.598	
е	2.540TYP.		0.100TYP		
F	2.700REF		0.10	6REF	
Φ	3.500REF		0.138REF		
h1	0.800REF		0.03	1REF	
h2	0.500REF		0.020REF		
L	28.000	28.400	1.102	1.118	
L1	1.700	1.900	0.067	0.075	
L2	1.900	2.100	0.075	0.083	

http://www.ncepower.com

NCE0224F

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